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U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10083991	02/26/2002	438	424	2812	Isaac

\*\*APPLICANTS: Chang Chia-Der; Yen Yi-Tung;

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:

PG-PUB DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	TS01-660
Verified and Acknowledged Examiners's initials <i>Harvella Law SDT</i>	
TITLE : Planarization method for deep sub micron shallow trench isolation process	
U.S. DEPT. OF COMM./PAT. & TM-PTO-435L (Rev. 12-94)	

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
Assistant Examiner		Application Examiner	
Primary Examiner			
PREPARED FOR ISSUE			
<input type="checkbox"/> TERMINAL DISCLAIMER		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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